



60V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = +25°C
-60V	150mΩ @ V _{GS} = -10V	-3A
-00 V	185mΩ @ V _{GS} = -4.5V	-2.7A

Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Motor Control
- Transformer Driving Switch
- DC-DC Converters
- Power Management Functions
- Uninterrupted Power Supply

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) test in production
- Low on-resistance
- Fast switching speed
- Lead-Free Finish; RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

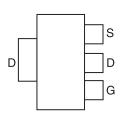
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- · Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame.
 Solderable per MIL-STD-202, Method 208 3
- Weight: 0.112 grams (approximate)

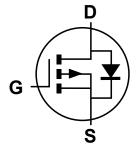
SOT223



Top View



Pin Out - Top View



Equivalent Circuit

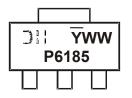
Ordering Information (Note 4)

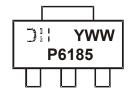
Part Number	Qualification	Case	Packaging
DMP6185SE-13	Standard	SOT223	2,500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information





311 = Manufacturer's Marking
 P6185 = Marking Code
 YWW = Date Code Marking for SAT (Shanghai Assembly/ Test site)
 YWW = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Y or \overline{Y} = Year (ex: 3 = 2013) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source voltage		V_{DSS}	-60	V	
Gate-Source voltage		V_{GS}	±20	V	
Continuous Drain current (Note 6) V = 10V	T _A = +25°C		-3	^	
Continuous Drain current (Note 6) V _{GS} = -10V	T _A = +70°C	ΙD	-2.4	A	
Maximum Body Diode Continuous Current		Is	-2	Α	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)		I _{DM}	-15	Α	
Single Pulsed Avalanche Current (Note 7)		I _{AS}	-16	A	
Single Pulsed Avalanche Energy (Note 7)		E _{AS}	13	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)	T _A = +25°C	D	1.2	W
Total Power Dissipation (Note 5)	T _A = +70°C	P_{D}	0.8	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	D	104	°C/W
Thermal Resistance, Junction to Ambient (Note 3)	t<10s	$R_{\theta JA}$	51	
Total Dower Dissination (Note 6)	T _A = +25°C	6	2.2	w
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	P_{D}	1.4	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	60	°C/W
memial Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	30	
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	7.6	
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

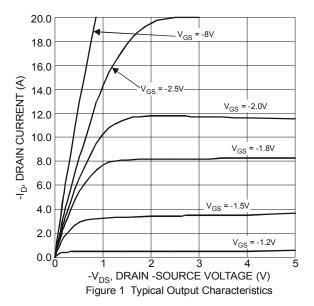
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

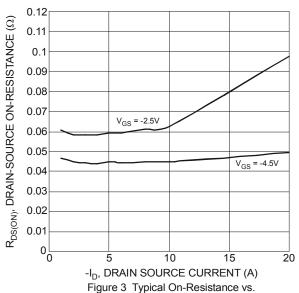
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-60	_	_	V	V _{GS} = 0V, I _D = -250μA	
Zero Gate Voltage Drain Current	IDSS	-	_	-1	μA	$V_{DS} = -48V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)	1633	<u> </u>				VG3 120V, VD3 01	
Gate Threshold Voltage	V _{GS(th)}	-1	_	-3	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
			110	150		$V_{GS} = -10V, I_D = -2.2A$	
Static Drain-Source On-Resistance	R _{DS} (ON)	_	130	185	mΩ	V _{GS} = -4.5V, I _D = -1.8A	
Diode Forward Voltage	V _{SD}	_	-0.75	-0.95	V	V _{GS} = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 9)		<u> </u>		1		1 00 : 7 0	
Input Capacitance	C _{iss}	-	708	=	pF		
Output Capacitance	Coss	-	39	-	pF	$V_{DS} = -30V, V_{GS} = 0V,$	
Reverse Transfer Capacitance	C _{rss}	-	32	=	pF	f = 1MHz	
Gate Resistance	Rg	-	17	28	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	-	6.2	-	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	-	14	=	nC	1,, 20,, 1 - 404	
Gate-Source Charge	Q _{gs}	-	2.8	_	nC	$V_{DS} = -30V, I_{D} = -12A$	
Gate-Drain Charge	Q _{gd}	-	3.1	=	nC	1	
Turn-On Delay Time	t _{D(on)}	-	5.2	_	ns		
Turn-On Rise Time	tr	-	23	-	ns	$V_{DS} = -30V, R_{L} = 2.5\Omega$	
Turn-Off Delay Time	t _{D(off)}	-	33	-	ns	$V_{GS} = -10V$, $R_G = 3\Omega$	
Turn-Off Fall Time	t _f	-	39	_	ns	7	
Body Diode Reverse Recovery Time	t _{rr}	-	22	=	ns	1 404 11/14 4004/	
Body Diode Reverse Recovery Charge	Q _{rr}	-	17	-	nC	I _F = -12A, di/dt = 100A/μs	

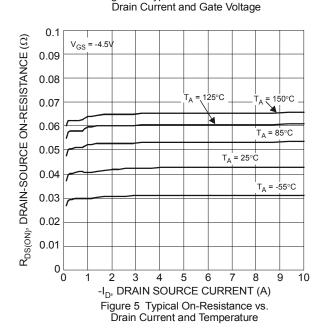
Notes:

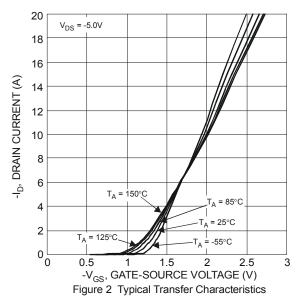
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. UIS in production with L = 0.1mH, starting $T_A = +25$ °C.
- Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

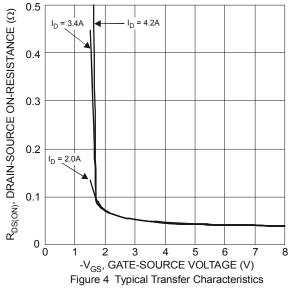


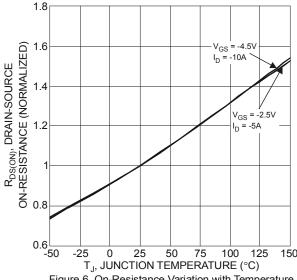




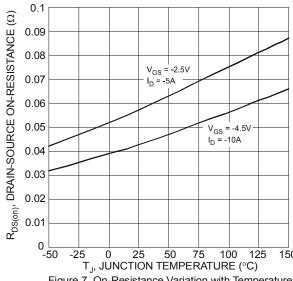


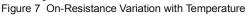


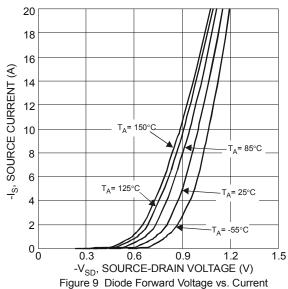


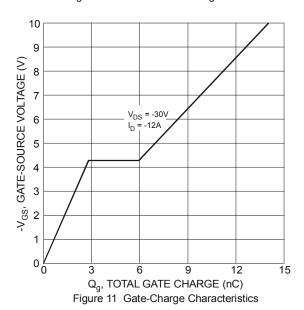












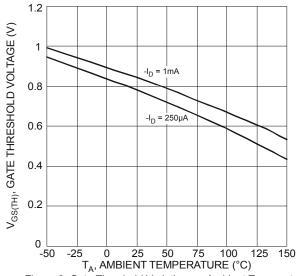
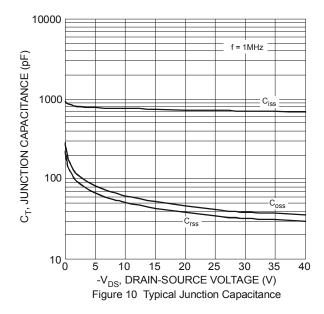
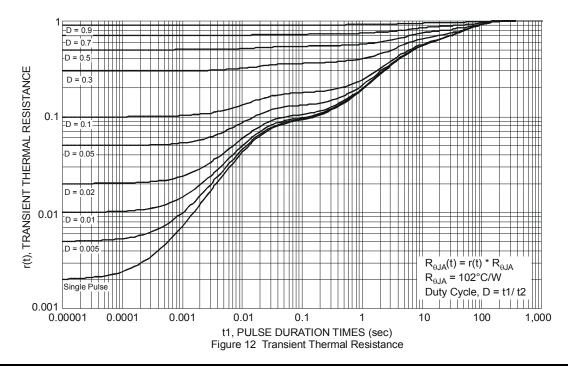


Figure 8 Gate Threshold Variation vs. Ambient Temperature

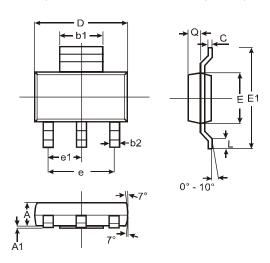






Package Outline Dimensions

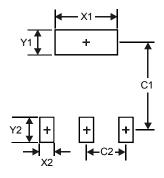
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b1	2.90	3.10	3.00		
b2	0.60	0.80	0.70		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	_	_	4.60		
e1		_	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
X1	3.3			
X2	1.2			
Y1	1.6			
Y2	1.6			
C1	6.4			
C2	2.3			



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2014, Diodes Incorporated

www.diodes.com